DFI

Desire
For
Innovation

Edge AI: A Strategic, Practice-Driven Transformation

Built on DFI's Industry-Proven, Mission-Critical Edge AI Platforms

intel **prestige** partner **Builder**

www.dfi.com

Accelerating Edge AIoT Transformation with DFI

Founded in 1981, DFI Inc. is a global leader in high-performance Edge AI computing of industrial computing portfolios, recognized for its innovative designs, reliable manufacturing, strict version control, long-term supply, and longevity support for industrial applications. Through continuous innovation and close collaboration with global partners, DFI empowers customers to build the most competitive and future-ready industrial computing portfolios, enabling smarter, faster, and more resilient operations at the edge.

| Established |
| --- |
| 1981 |
| **Headquarters** |
| Taipei, Taiwan |
| **Global Footprint** |
| **Sales Offices:** United States, Netherlands, Japan, China, Taiwan, Korea, India, Vietnam, and Germany
Manufacturing Centers: Taiwan, China, Vietnam, and other long-term CM partners |
| **Total Employees** |
| Approximately 665, including over 180 R&D professionals |

Driving Innovation in Edge AI Worldwide

DFI is the trusted backbone for mission-critical AI applications. From smart factories and healthcare to intelligent transportation and entertainment, we ensure precision everywhere. This reliability extends to the harshest environments in energy, mining, and defense. Beyond these sectors, we push the boundaries of computing to enable innovation in the most unexpected places.

Explore Success Stories
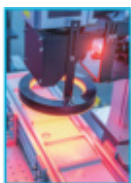
Machine Vision

Object Detection & Classification

AMRs & SLAM Tech.

Robotic AI & Control Tech.

Medical AI

UAV Applications

Traffic Management

AI-Driven Detection & Communication

Surveillance & Security

Next in Edge AI

And More...

Thrive with DFI on Your Next Project

When customers encounter new challenges or evolving demands, DFI responds with agility and innovation to deliver timely and scalable solutions. In addition to COTS products such as industrial motherboards, embedded systems, Edge AI servers, and panel PCs, DFI also provides Design Manufacturing Services to meet specific application requirements and customized designs.

Deep Partnership with Key Vendors

- DFI partners with leading chipset vendors such as Intel, AMD, NVIDIA, NXP, Qualcomm, MediaTek, Rockchip, DEEPX, and Hailo.

- With Edge AI integration and partnerships with Canonical and Microsoft, DFI delivers secure, reliable IoT systems.

Driving Innovation & Quality Forward

- DFI follows DFM principles and a rigorous design review process, covering schematic design, placement and layout optimization, and MTBF analysis.

- All DFI product undergoes comprehensive validation processes, guaranteeing customers consistent, top-tier performance and reliability.

DFI Plus Group Synergy

- DFI's in-house design and manufacturing ensure timely, reliable delivery.

- Backed by Qisda Group's global resources, DFI fulfills customer needs with agility and scale.

Desire for Innovation COTS & DMS

- Accelerate time-to-market with DFI's COTS-based portfolio.

- Through DMS services, we deliver world-class integration, supply chain, and cost management to simplify your design challenges.

DFI's Edge AIoT Computing Portfolios

Factory Automation

Gaming / Infotainment

Resilience in Every Edge Moment

DFI delivers reliable and scalable industrial computing products across industries such as defense, automation, gaming, medical, transportation, and energy. With deep expertise and flexible ODM/O-EM support, DFI provides both COTS offerings and customized DMS designs.

As a leader in Edge AI innovation, DFI combines robust hardware and advanced AI computing to accelerate intelligent transformation from the Far Edge to the Near Edge.

Backed by strong R&D and a global supply chain, DFI's portfolio includes industrial motherboards, SBCs, SoMs, systems, Edge AI servers, panel PCs, peripherals, and AI modules.

Far Edge to Near Edge — Tailored to Your Needs

Far Edge (<300 TOPs)

ARM	
CPU + NPU	Qualcomm MEDIATEK NXP Rockchip nVIDIA

CPU (+NPU) intel ATOM intel CORE

Wide Range Industrial Edge AIoT Computing COTS /

Industrial Motherboards

Mini-ITX	microATX	ATX	EATX

Single-board Computers

1.8"	2.5"	3.5"	4"	PICMG1.3

System-on-Modules

OSM	Qseven	SMARC	COMe Mini	COMe Compact	COMe Basic	COM HPC

Defense/Marine **Medical** **Transportation** **Gas/Oil/Energy**

Near Edge (Up to 7 PCIe Slots)

x86

intel CORE ULTRA 7 | intel XEON | AMD RYZEN Embedded | GPU (or M.2 NPU) NVIDIA | intel ARC GRAPHICS | DEEPX | memryX HAILO

x86

CPU intel XEON | AMD EPYC | GPU NVIDIA

DMS Services

Industrial Systems

Compact & Fanless Platforms **Expandable Platforms** **NVIDIA Platforms** **IP67/IP69K Ruggedized Platforms**

Edge AI Servers

1U/2U/4U Servers

Panel PCs

Fanless Platform **Open Frame** **Expandable Platform**

Peripherals

OOB Modules **Connection Modules** **Display Modules**

AI Acceleration Modules

MXM/PEG GPU **M.2 NPU**

NVIDIA | intel ARC GRAPHICS | memryX DEEPX HAILO

One-Stop
Design & Manufacturing Services

From Design to Market

At DFI, we deliver more than products—we provide a comprehensive one-stop service that covers every stage of the product lifecycle.

01
DFM Alignment
DFI experts apply DFM principles and work closely with customers to refine designs, specifications, and BOMs—extending product lifespans and ensuring every delivery meets the highest quality standards.

02
Tailored Customization & Validation
Beyond COTS products, DFI delivers custom x86/ARM-based platforms, rapid prototyping, power and signal validation, performance optimization, and full certification to meet diverse industry requirements.

03
Value-Added Technology Integration
Enhancing product capability with software integration (Windows, RTOS, Ubuntu, Android), BIOS/firmware optimization (Slim Bootloader, fast resume, 1W standby), AI acceleration, and Out-of-Band modules—addressing the evolving needs of smart applications.

04
100% In-House Production
From PCB assembly to final testing, DFI's fully in-house production process ensures supply chain stability, minimizes risks, and maintains consistent product quality for every application.

05
After Service & Lifecycle Support
Comprehensive post-production support—including repairs, upgrades, reorders, and BOM management—ensures continuous lifecycle service and long-term reliability.

Beyond Design Manufacturing Services

From design-in collaboration to after-service support, DFI's dedicated engineering team serves as your trusted joint design collaborator or exclusive ODM/OEM partner, providing end-to-end technical expertise. Through comprehensive DFM analysis, our engineers ensure optimal product design for production efficiency and long-term reliability. The team also identifies alternatives for EOL or supply-constrained components, assists with redesign and troubleshooting, and manages revision control and engineering change processes with precision. In addition, DFI offers flexible material planning strategies to mitigate long lead times and maintain stable product supply.

Design / Assembly / Manufacturing Expertise

Motherboards	Single Board Computers	System on Modules	Systems	Edge Servers

Panel PCs/ Displays	KIOSK	Peripherals	FW/BIOS/ Driver/OS

R&D Capabilities

- Thermal
- Power Design
- Mechanical Engineering
- EMC Compatibility
- Electrical Engineering
- Radio Frequency
- Simulation
- FAE

QA & QC

- Modular Design
- TQM
- Power Validation
- Environment Reliability
- Singal Integrity
- DQA

Reliable AI, Ruggedized by DFI
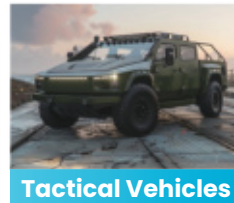
Durable, Stable, Anytime, Anywhere

USVs

Agriculture

Mining

Factories

Tactical Vehicles

Ports

DFI's latest ruggedized system is built for the demands of mission-critical Edge AI and automation control. Combining an IP-rated design with industrial-grade durability, it delivers flawless performance in extreme conditions. We ensure long-term reliability through rigorous validation, including HALT, -40°C to 85°C support, and MIL-STD compliance. Furthermore, we offer one-stop design and manufacturing services tailored to your specific project requirements, ensuring the system meets the exact standards needed for your toughest deployments.

Engineered for Reliability, Built to Last

Design Stage

DFM-Oriented Design Expertise – Engineered with deep understanding of each customer's application and operational needs.

Proven Reliability – Ensured through precise component selection, de-rating analysis, MTBF evaluation, and thermal/mechanical optimization.

Validation Stage

World-Class Testing & Validation – In-house facilities supporting HALT and MIL-STD-compliant shock and vibration testing.

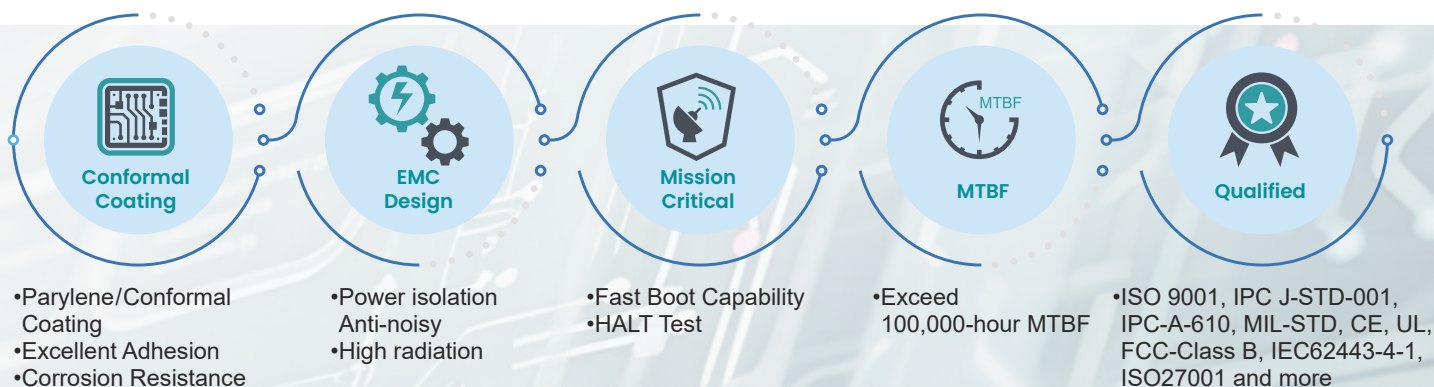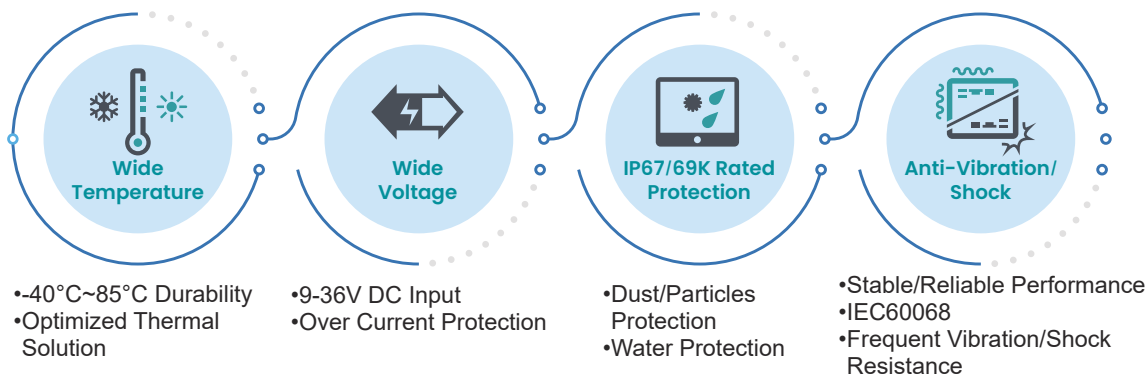**EMC Class B Compliance –** Verified and tailored to meet specific customer requirements.

Production Stage

IPC Class 3 Certified Manufacturing – Advanced IPC assembly expertise meeting the highest standards under the latest revision.

ETT Screening for CPU SKUs – Ensures exceptional reliability in extended temperature and harsh environments.

Our Core Rugged Capabilities

Wide Temperature
- -40°C~85°C Durability
- Optimized Thermal Solution

Wide Voltage
- 9-36V DC Input
- Over Current Protection

IP67/69K Rated Protection
- Dust/Particles Protection
- Water Protection

Anti-Vibration/Shock
- Stable/Reliable Performance
- IEC60068
- Frequent Vibration/Shock Resistance

Conformal Coating
- Parylene/Conformal Coating
- Excellent Adhesion
- Corrosion Resistance

EMC Design
- Power isolation Anti-noisy
- High radiation

Mission Critical
- Fast Boot Capability
- HALT Test

MTBF
- Exceed 100,000-hour MTBF

Qualified
- ISO 9001, IPC J-STD-001, IPC-A-610, MIL-STD, CE, UL, FCC-Class B, IEC62443-4-1, ISO27001 and more

ECX700-ASL
- Rugged IP67/IP69K design with vibration, shock resistance, and -40°C~70°C wide temperature operation
- Intel® Atom® X7433RE/X7835RE CPU with up to 16GB LPDDR5 memory
- Rich Waterproof I/O & Expansion: dual 2.5GbE, USB 3.2, HDMI, antenna ports, combo I/O, 9–36V DC input, and support for Wi-Fi/BT, 4G/5G

ECX700-ADP
- Rugged IP67/IP69K design with vibration and shock resistance, and -20°C to 70°C wide-temperature operation
- Powered by 12th Gen Intel® Core™ i5-1245UE/i7-1265UE with onboard 8GB DDR4 plus one SODIMM (up to 32GB)
- Rich Waterproof I/O & Expansion: dual GbE, USB 3.2, HDMI, COM/CAN bus, antenna ports, IP67 vent, 9–36V DC input, and support for Wi-Fi/BT, 4G/5G

TAIWAN EXCELLENCE 2026

V6Xα-ORN
- NVIDIA® Jetson Orin Nano™/NX edge AI platform for advanced in-vehicle AI applications
- Rugged Fanless Design: IP67-rated, 9–36VDC input with ignition control, and optional configuration to -40°C~70°C operation
- Flexible Connectivity: optional Wi-Fi 6E/4G/5G and camera interfaces via USB 3.0, GMSL2, or PoE

Industrial System

Ultra Compact Fanless System

EC70A-MTH
- Intel® Core™ Ultra 7/5 processors with up to 32GB LPDDR5 6400MHz memory
- Dual Display: HDMI (4K@24Hz) and USB-C (DP Alt Mode)
- Rich Expansion & I/O: M.2 B Key (5G-NR), triple LAN, multiple USB, COM, and HDMI

EC900-QCS
- Qualcomm® QCS6490 platform with 8 cores up to 2.7GHz and 12 TOPS AI performance
- Onboard LPDDR5x memory up to 8GB with M.2 expansion for Wi-Fi/BT and LTE
- Rich I/O: USB 3.1, GbE LAN, HDMI, audio, COM, DIO, and CAN FD

EC700-ASL / EC710-ASL
- Intel® Processor Industrial RE Series with onboard DDR5, fanless design with built-in OOB and Intel® TCC support
- Quad Display: HDMI, USB-C, VGA, and DisplayPort

EB100-MTU
- Industrial NUC system powered by Intel® Core™ Ultra 5/7 processors with up to 48GB DDR5 memory
- Fanless compact design: 111 × 50 × 106 mm, 12VDC input, operating from -20°C to 50°C
- Rich Expansion & I/O: M.2 E/M Key, dual 2.5GbE (TSN/TCC), USB, Type-C, and serial ports

AI Inference System

X6-MTH-ORN
- Hybrid architecture combining Intel® Core™ Ultra processor and NVIDIA Jetson Orin NX (up to 157 TOPS)
- DFI OOB module for remote management and OTA updates
- Rich Expansion & I/O: multiple M.2 slots, PoE LANs, USB, COM, CAN bus, HDMI, VGA, and audio

V6Xa-ORN
- NVIDIA® Jetson Orin Nano™/NX edge AI platform for advanced in-vehicle AI applications
- Rugged Fanless Design: IP67-rated, 9–36VDC input with ignition control, and optional configuration to -40°C~70°C operation
- Flexible Connectivity: optional Wi-Fi 6E/4G/5G and camera interfaces via USB 3.0, GMSL2, or PoE

DT200-CS
- 8th/9th Gen Intel® Core™ Processors
- Supports up to 115W GPU MXM for AI acceleration
- Multiple displays with rich I/O and 5G connectivity

X6a-AGX
- NVIDIA Edge AI engine: NVIDIA® Jetson Orin AGX™ module (max. 275 TOPs)
- Flexible Connectivity: multiple GbE ports with optional PoE and OOB support
- Rich Expansion & I/O: M.2 slots, audio, RS232, CAN bus, USB, and HDMI
- Optional Capture card and Camera Interfaces: SDI, HDMI and GMSL2 input

Embedded Fanless System

EC600-RPS / EC622-RPS / EC633-RPS / EC633D-RPS
- Industrial expandable systems powered by14th/13th/12th Gen Intel® Core™ processors with Intel® R680E chipset and up to 64GB DDR5 memory
- Comprehensive Expansion: up to 5 M.2 slots, mini-PCIe, and 5G communication support
- Rich I/O & Wide Temperature: 2× 2.5GbE, 4× GbE, USB 3.2, Type-C, HDMI, DP++, VGA, 9 COM, and -20°C to 70°C operation

Ruggedized System

ECX700-ASL
- Rugged IP67/IP69K design with vibration, shock resistance, and -40°C~70°C wide temperature operation
- Intel® Atom® X7433RE/X7835RE CPU with up to 16GB LPDDR5 memory
- Rich Waterproof I/O & Expansion: dual 2.5GbE, USB 3.2, HDMI, antenna ports, combo I/O, 9–36V DC input, and support for Wi-Fi/BT, 4G/5G

ECX700-ADP
- Rugged IP67/IP69K design with vibration and shock resistance, and -20°C to 70°C wide-temperature operation
- Powered by 12th Gen Intel® Core™ i5-1245UE/i7-1265UE with onboard 8GB DDR4 plus one SODIMM (up to 32GB)
- Rich Waterproof I/O & Expansion: dual GbE, USB 3.2, HDMI, COM/CAN bus, antenna ports, IP67 vent, 9–36V DC input, and support for Wi-Fi/BT, 4G/5G

Edge AI Server & Computer

Rackmount 4U Server

RM840-PR810
- 4U 19" rackmount server with dual Intel® 1st/2nd Xeon® Scalable processors
- Flexible expansion options: 4 PCIe x16 and FH/10.5" GPU card insert available
- Rich I/O : 2 Intel 10GbE, 2 Intel GbE, 2 COM, 8 SATA 3.0, 5 USB 2.0, 6 USB 3.1 Gen1

RM645-SO630
- 4U short-depth edge server powered by AMD® EPYC™ Embedded 3451/3351 processors with up to 256GB DDR4 memory
- Flexible Expansion: 3 PCIe x16 and FH/10.5" GPU card insert available
- High Expandability & Storage: supports single-slot GPU/IO cards, 3.5"/2.5" drive bays

RM646-ERX810
- 4U 19" rackmount server with dual 4th/5th Gen Intel® Xeon® Scalable processors delivering powerful AI computing performance
- Up to three dual-slot GPUs with PCIe Gen5 support for accelerated AI workloads
- High Expandability & I/O: 5 hot-swappable 3.5" drive bays, GbE, IPMI LAN, USB, DP, M.2, and MCIO

RM645-ERX810
- 4U 19" rackmount server with dual 4th/5th Gen Intel® Xeon® Scalable processors delivering exceptional computing performance
- High Expandability & Storage: 4 x PCIe x16 and FH/10.5" GPU card insert available, 3.5"/2.5" drive bays, E1.S storage bays
- Comprehensive I/O & Management: GbE, IPMI LAN, USB, DisplayPort, M.2, COM, and IPMI-based remote management

Rackmount 1U Server
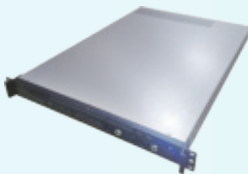
RM810-ERX810
- 1U 19" rackmount server with dual 4th/5th Gen Intel® Xeon® Scalable processors delivering exceptional computing performance
- High Expandability & Storage: supports single-slot GPU cards and four hot-swappable 3.5"/2.5" drive bays
- Comprehensive I/O & Management: GbE, IPMI LAN, USB, DisplayPort, M.2, COM, and IPMI-based remote management

Medical-Grade Server

MPC350-RPS
- Medical-grade Edge AI Inference Server powered by 14th/13th/12th Gen Intel® Core™ processors with Intel® R680E chipset
- High Performance & Expandability: supports NVIDIA® Quadro/RTX 6000 Ada GPU and dual-channel video capture card
- Hygienic & Reliable Design: easy-to-clean enclosure, IEC60601-1/60601-1-2 compliant

Wall Mount IPC

WM343-RPS
- Wall-mount computer and supports 14th/13th/12th Gen. Intel® Core™ CPUs with up to 65W TDP
- 1x PCIe Gen5 x16 slot –FH/9.5" GPU cards available for high-performance graphics or AI acceleration
- Comprehensive I/O options – includes Intel® 2.5GbE & 1GbE LAN, 4x USB 3.2, 2x USB 2.0, COM, PS/2, Line-out, Mic-in

WM140-RPS
- Height limited of wall mount system for 14th/13th/12th Generation Intel® Core™ Processors
- Storage & Expansion: 1× 2.5" SATA bay and 1 x PCIe x16 Gen5 supports low-profile GPU upto 75W
- Triple display support and rich I/O: 2 Intel 2.5GbE, 6 USB 3.2 Gen1, 2 COM

WM130-RPS
- Small scale of wall mount system for 14th/13th/12th Generation Intel® Core™ Processors
- Storage & Expansion: 1× 2.5" SATA bay and 1 x PCIe x16 Gen5 supports single slot up to 75W
- DC-in 12~28V and Optional I/O openings for up to 4 USB and 3 DB9 ports

Industrial Motherboard

Mini-ITX

RPS183
- Intel® Core™ BTL-S / 14th / 13th / 12th Gen processors with Intel® Q670E/H610E chipset and up to 64GB DDR5 memory
- Multiple Displays: 2x DP++, USB Type-C (DP Alt-mode), HDMI, and eDP with 4K resolution support
- Multiple Expansion & Rich I/O: 1× PCIe Gen4 x4, 1x MXM, 1× M.2 M-key (PCIe/SATA), 1× M.2 E-key, 1x M.2 B-Key; 2× 2.5GbE, 2× COM, 6× USB 3.2 (Gen2/Gen1), and 1× SATA

PTH171/PTH173
- Next-generation Intel® Core™ Ultra processors with TDP up to 25W, supporting up to 128GB DDR5 6400/7200MHz
- Quad display: 4× or 3× DP++ + 1× M.2 A-key display
- Multiple Expansion & Rich I/O: 1× PCIe Gen5 x4, 1× M.2 M-key (NVMe), 1× M.2 B-key (4G/5G with SIM), 1× M.2 E-key (Wi-Fi/BT), 1× M.2 A-key; up to 3× Intel 2.5GbE, 2× COM, 4× USB 3.2 Gen2 Type-A, 1× USB-C, 5× USB 2.0 headers, 2× SATA 3.0

HPT171
- AMD® Ryzen™ Embedded 8000 Series Processors with 2 DDR5 5600MHz SODIMM up to 64GB
- Quad display: 4 DP++ or 3 DP++ + 1 M.2 A display
- Multiple expansion: 1 PCIE Gen4 x16 Slot (x8 Signal), 1 M.2 M key (PCIE/SATA), 1 M.2 A key (LVDS/eDP/HD-MI/DP/VGA) and M21(PCIE/SIM/USB3/USB2) module support, 1 DFI eMMC modular port
- Rich IO :2 2.5GbE RJ45, 2 USB 3 Type- A, 2 USB2.0 Type A, 2 COM D-Sub,1 Audio Jack Line-IN/Line-OUT/Mic-IN, 4 RS232(ccTalk/TTL), 4 USB2.0 headers, Gaming I/O(PCIE,UART/USB2.0, Audio), Support EXT-OOB (Full)

Micro-ATX

ARS310-W880/Q870
- Intel® Core™ Ultra processors with Intel® W880/Q870 chipset and up to 256GB DDR5 memory
- Quad Display: VGA, 2× DP++, and HDMI with 4K resolution support
- Multiple Expansion & Rich I/O: 2× PCIe Gen5 x16 (x16 or x8+x8), 2× PCIe x4, 2× M.2 M-key (PCIe/SATA), 1× M.2 E-key, 2x 10GbE, 2× 2.5GbE, 6× COM, 10 USB 3.2 (Gen2/Gen1), and 4× SATA

RAP310-B650
- AMD® Ryzen™ 9000/7000/EPYC™ 4005 Series processors with AMD B650 chipset and up to 128GB DDR5 memory
- Triple Display: VGA, DP++, and HDMI with 4K resolution support
- Multiple Expansion & Rich I/O: 2× PCIe Gen4 x16 (x16 or x8+x8), 2× PCIe x4, 1× M.2 M-key (PCIe), 1× M.2 E-key; 2× 2.5GbE, 4× COM, 8 USB 3.2 (Gen2/Gen1), and 4× SATA

ATX

ARS630-W880/Q870
- Intel® Core™ Ultra processors with Intel® W880/Q870 chipset and up to 256GB DDR5 memory
- Quad Display: VGA, 2× DP++, and HDMI with 4K resolution support
- Multiple Expansion & Rich I/O: 2× PCIe Gen5 x16 (x16 or x8+x8), 4× PCIe x4, 1× PCI, 2× M.2 M-key (PCIe/SATA), 1× M.2 A-key (OOB); 4× 2.5GbE, 6× COM, 10 USB 3.2 (Gen2/Gen1), and 4× SATA

BTS610-W680/R680E/Q670E
- Intel® Core™ BTL-S / 14th / 13th / 12th Gen processors with Intel® W680/R680E/Q670E chipset and up to 192GB DDR5 memory
- Quad Display: VGA, 2× DP++, and HDMI with 4K resolution support
- Multiple Expansion & Rich I/O: 2× PCIe Gen5 x16 (x16 or x8+x8), 5× PCIe x4, 2× M.2 M-key (PCIe/SATA), 1× M.2 A-key (OOB); 4× 2.5GbE, 6× COM, 10× USB 3.2 (Gen2/Gen1), and 4× SATA

SNA610
coming soon
- AMD EPYC™ 8004 processors with up to 576GB DDR5 ECC RDIMM memory
- Single Display: DP
- Rich Expansion & I/O: PCIe Gen5 x16/x8/x4, M.2, dual GbE + dual 10GbE, IPMI LAN, USB, and COM interfaces

ERX610-C741
- 5th/4th Gen Intel® Xeon® Scalable processors with up to 1TB DDR5 ECC RDIMM memory
- Single Display: DP
- IPMI/Redfish OOB remote management support
- Rich Expansion & I/O:3 PCIe x16 (Gen5), 3 PCIe x8 (Gen5), 2 M.2 M key 2280, 2 Intel® GbE, 2 Intel® 10GbE, 4 SATA 3.0, 6 USB 3.2, 2 USB 2.0, 1 Vertical USB 2.0, 2 COM, 1 Dedicated IPMI

EATX

ERX810-C741
- 5th/4th Gen Intel® Xeon® Scalable processors with up to 2TB DDR5 ECC RDIMM memory
- Single Display: DP
- IPMI/Redfish OOB remote management
- Rich Expansion & I/O:4 PCIe x16 (Gen 5), 2 PCIe x8 (Gen5), 1 M.2 M key 2280, 4 Intel® GbE, 1 Dedicated IPMI, 2 COM, 4 SATA 3.0, 6 USB 3.2 Gen1, 2 USB 2.0, 1 Vertical USB 2.0

1.8" SBC

PCSF51
- AMD Ryzen™ Embedded R2000 Series (Picasso) 1.8" SBC for space-limited applications
- Single-channel DDR4 memory down up to 8 GB and eMMC storage up to 128 GB
- Supports HDMI 1.4 resolution up to 4096 × 2160 @ 24 Hz

2.5" SBC

QCS051
- Qualcomm QCS6490 high-performance platform designed for AMR and box PC applications
- Built on a thin client concept with ruggedized design
- Features dual M.2 expansion slots: 1 M.2 E Key 2230 and 1 M.2 B Key 3052

M93053
- NXP i.MX93 platform for entry-level applications
- Wide 9–36V DC input with dual GbE LAN for automation
- Supports CAN bus and M.2 3042 expansion

3.5" SBC

MTH556
- Powered by Intel® Core™ Ultra Processor with 2 DDR5 5600MHz SODIMM up to 96GB
- Supports 4K resolution and triple independent displays via HDMI, LVDS, and USB-C DP Alt Mode
- Multiple M.2 expansions (1 E Key, 1 B Key, 1 M Key) with rich I/O including 2 2.5GbE, 4 COM, and 6 USB ports

IRN556
- Powered by Intel® Atom x7000RE series (Amston Lake/Twin Lake) with DDR5 4800MHz SODIMM up to 16GB
- Supports dual displays via HDMI and LVDS
- Multiple M.2 expansions (1 E Key, 1 B Key, 1 M Key) with rich I/O including 2 GbE, 4 COM, and 6 USB ports

ASL553
- Intel® Atom® Amston Lake 3.5" SBC with DDR5 4800MHz SODIMM up to 16GB
- Supports 4K resolution and triple displays via HDMI, Type-C DP Alt Mode, and LVDS/eDP (opt.)
- Rich I/O with 3 2.5GbE LAN, 6 USB, 1 SATA, and 3 M.2 expansions, supporting -40°C to 85°C wide temperature range

RPP051
- 13th Gen Intel® Core™ processors for space-limited applications
- Up to 32GB DDR5 4800MHz memory and dual 4K displays via DP++ and eDP
- Multiple M.2 expansions (E/B Key) with rich I/O including 2.5G LAN, COM, and USB ports

ASL051
- Intel® Atom x7000RE series (Amston Lake) with 1 DDR5 4800MHz SODIMM
- Supports 4K/2K resolution and dual displays via HDMI + LVDS/eDP (opt.)
- Multiple M.2 expansions (E/B Key) with rich I/O including dual 2.5GbE, COM, and USB ports

4" SBC
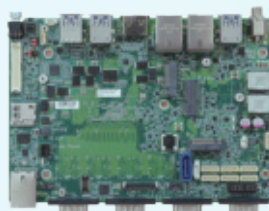
MTH253
- Powered by Intel® Core™ Ultra Processor with dual channel LPDDR5x 6400MHz memory down up to 32GB
- Supports triple displays via HDMI, LVDS, and Type-C DP Alt Mode
- Multiple M.2 expansions (1 E Key, 1 B Key, 1 M Key) with rich I/O including 2 2.5GbE, 1 GbE, 7 USB, and 6 COM ports

ASL253
- Intel® Atom® Amston Lake Series with Intel® TCC support
- High-speed LPDDR5 4800MHz memory, SATA III, and M.2 storage
- Supports up to quad display (HDMI/USB-C/eDP) with rich I/O including 2.5GbE, GbE, USB, and COM ports
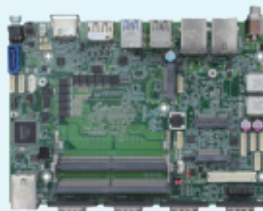
HPT253
- Powered by AMD® Ryzen™ Embedded 8000 Series Processors
- Supports up to 96GB DDR5 5600MHz and quad displays via DP, HDMI, LVDS, and Type-C DP Alt Mode
- Multiple M.2 expansions (M/B/E Key) with rich I/O including 2.5GbE, GbE, USB, and COM ports

EHL253
- Intel® Atom® X Series with onboard DDR4 and one DDR4 3200MHz SODIMM
- Supports dual independent 4K displays via VGA and DP++
- Multiple M.2 expansions (E/B/M Key) with rich I/O including 2.5GbE, GbE, USB, COM, and SATA 3.0

System-on-Module

OSM

QRB812
- Powered by Qualcomm QRB5165 processor with 8x Kryo 585 cores and 8GB LPDDR5 memory
- Supports dual displays via MIPI-DSI and USB-C DP
- Multiple interfaces including PCIe, USB 3.1, and MIPI-CSI for AMR, robotics, and drone applications

SMARC

ASL600
- Intel® Atom x7000RE Series (Amston Lake) Processors
- Onboard LPDDR5 4800MHz up to 16GB and triple 4K displays via LVDS/eDP, HDMI, and DDI
- Multiple PCIe interfaces and rich I/O including dual 2.5GbE, USB 3.2, and SATA 3.0

COMe Mini

MTU9A2
- Intel® Core™ Ultra (Meteor Lake U-series) with up to 32GB LPDDR5 7467MHz memory
- Supports dual 4K displays via DDI and eDP
- Multiple interfaces (PCIe, I2C, SMBus, eSPI, UART) with rich I/O including 2.5GbE, USB, and SATA 3.0

ADN9A2
- Intel® Atom® Alder Lake-N Series with dual-channel LPDDR5 4800MHz up to 16GB
- Supports dual displays via DDI (HDMI/DP++) and LVDS/eDP
- Multiple interfaces including PCIe, SMBus, I2C, eMMC, with rich I/O and up to 2.5GbE Ethernet

ASL9A2
- Intel® Atom® Amston Lake Series with dual-channel LPDDR5 4800MHz up to 16GB
- Supports dual displays via DDI (HDMI/DP++) and LVDS/eDP
- Multiple interfaces including PCIe, SMBus, I2C, eMMC, with rich I/O and up to 2.5GbE Ethernet

COMe Compact

MTH966
- Powered by Intel® Core™ Ultra (Meteor Lake U/H-series) with up to 32GB dual-channel LPDDR5 7467MHz memory
- Supports 4K resolution and multiple displays via LVDS/eDP + 3 DDI
- Extensive interfaces including PCIe, I2C, SMBus, LPC/eSPI, and rich I/O with 2.5GbE, USB, and SATA 3.0

MTH968
- Powered by Intel® Core™ Ultra (Meteor Lake U/H-series) processors
- Supports up to 96GB DDR5 5600MHz and 4K quad displays via VGA, LVDS/eDP + 2 DDI
- Multiple PCIe lanes and rich I/O including 2.5GbE, USB 4.0, USB 3.2, and SATA 3.0

ASL968
- Powered by Intel® Core™ 3 & N Series (Twin Lake) and Atom® Amston Lake processors
- Supports up to 16GB DDR5 4800MHz and triple 4K displays via LVDS/eDP + 2 DDI
- Multiple PCIe lanes and rich I/O including 2.5GbE, USB 3.2, and SATA 3.0

RPP968
- Powered by Intel® Core® Processor Raptor Lake Series
- Supports up to 64GB DDR5 5200MHz and triple displays via LVDS/eDP, VGA, and DDI (HDMI/DP++)
- Multiple PCIe expansions and rich I/O including GbE, USB 3.2, and USB 2.0

COMe Basic

ICD970
- Powered by 3rd Gen Intel® Xeon® D-1700 Family with up to 64GB DDR4 2933MHz memory
- Supports extended temperature range from -40°C to 85°C and up to 4×10GbE ports
- Multiple PCIe, SMBus, and I2C interfaces with rich I/O including GbE, USB, and SATA 3.0

TGH960
- 11th Gen Intel® Processor COM Express® Basic with up to 128GB DDR4 3200MHz memory
- Supports 4K resolution and multiple displays via VGA, LVDS*/eDP, and 3 DDI
- Multiple PCIe, LPC, I2C, and SMBus interfaces with rich I/O including 2.5GbE and USB ports

COM HPC

RPS9HC
- Powered by 14th/13th Gen Intel® Core™ processors with Intel® R680E/Q670E/H610E chipset
- Supports up to 192GB DDR5 and quad displays (eDP + 3 DDI) with up to 8K resolution
- Multiple PCIe expansions and rich I/O including dual 2.5GbE and USB 3.2 Gen2 ports

Panel PC

Fanless Platform

KS101P-MTH

- 10.1" TFT LCD Panel
- Intel® Core™ Ultra 7 155U / Ultra 5 125U processors delivering powerful performance for edge applications
- Projected capacitive touch with dual display support via HDMI and USB Type-C
- Multiple M.2 expansions (E/B/M Key) and wide 9–36V power input for flexible integration

KS156-ADN

- 15.6" TFT LCD Panel
- Intel® Atom® Alder Lake-N processors delivering efficient performance
- Projected capacitive touch with dual display support via HDMI and DP++
- Flexible expansion with M.2 B/E Keys and wide 9–36V power input

KS215P-TGU

- 21.5" TFT LCD Panel
- Intel® Core™ i5-1145GRE or Celeron® 6305E processors delivering reliable performance
- Projected capacitive touch with dual display support via HDMI and DP++
- Multiple M.2 expansions (M/B/E Key) with wide 9–36V power input

Open Frame

KIT-M8M Series

- Available in 7", 10.1", and 12.1" panel sizes
- NXP i.MX 8M processor with 10-point projected capacitive touch in an open-frame design
- Onboard 2GB LPDDR4-3200 and 16GB eMMC with M.2 B/E Key expansion
- ARM-based system supporting Android 9.0 and Yocto 4.3 for easy integration and maintenance

KIT-ADN Series

- Available in 10.1", and 12.1" panel sizes
- Supports Intel Alder Lake-N Series
- Industrial open-frame panel PC with 10-point P-Cap touch and LPDDR5-4800 memory
- Supports up to quad display via HDMI, USB-C, and LVDS

Expandable Platform

TPC150-RPS

- 15" TFT LCD Panel
- Supports triple display via DP++, HDMI, and VGA
- Equipped with 2×2.5" SATA bays, up to 64GB DDR5, and rich I/O including 2 GbE, 2 COM, 6 USB 3.2 Gen1, and Line-out
- Supports up to 165w 2 slot low-Profile graphics card

DFI

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For
Innovation

Founded in 1981, DFI is a global leading provider of high-performance computing technology across multiple embedded industries. With its innovative design and premium quality management system, DFI's industrial-grade solutions enable customers to optimize their equipment and ensure high reliability, long-term life cycle, and 24/7 durability in a breadth of markets including Industrial Automation, Medical, Infotainment,Transportation, Energy, Mission-Critical, and Intelligent Retail.